

TRF0206-SP 单通道、10MHz 至 6.5GHz、3dB 带宽、ADC 驱动器放大器

1 特性

- 已通过 QMLV (QML V 级) MIL-PRF-38535 认证, SMD 5962R2122001VXC
 - 耐辐射加固保障 (RHA) 能力高达 100krad (Si) 总电离剂量 (TID)
 - 单粒子锁定 (SEL) 抗扰度为 LET = 75 MeV-cm²/mg
- 支持军用级温度范围 -55°C 至 +125°C
- 可用作 ADC 驱动器, 具备出色的单端至差分转换性能
- 在差分至单端模式下运行, 用作 DAC 缓冲器
- 3dB 带宽: 6.5GHz
- 1dB 增益平坦度: 4.8GHz
- 单端至差分的固定功率增益为 12.5dB
- OIP3 性能:
 - 2GHz 时为 38dBm
 - 6GHz 时为 32dBm
- P1dB 性能:
 - 2GHz 时为 12dBm
 - 6GHz 时为 10dBm
- 噪声系数:
 - 2GHz 时为 8dB
 - 6GHz 时为 9dB
- 增益和相位不平衡: $\pm 0.4\text{dB}$ 和 $\pm 3^\circ$
- 关断特性
- 单电源运行: 3.3V
- 有效电流: 130mA

2 应用

- 射频采样或 GSPS ADC 驱动器
- [航天和国防](#)
- 高速数字转换器
- [雷达成像有效载荷](#)
- [命令和数据处理系统](#)
- [通信有效载荷](#)

3 说明

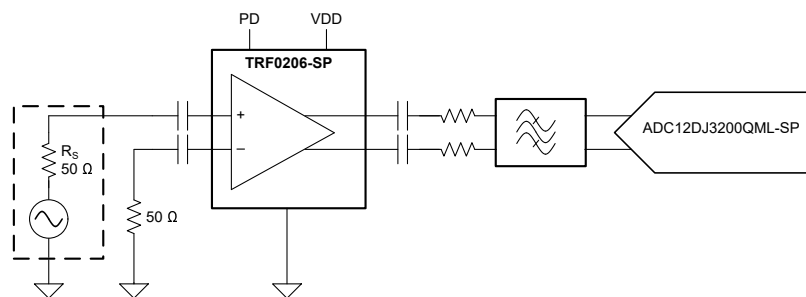
TRF0206-SP 是一款超高性能耐辐射射频 (RF) 放大器, 专门针对 RF 应用进行了优化。在驱动高性能 [ADC12DJ3200QML-SP](#) 等模数转换器 (ADC) 时, 交流耦合应用需要进行单端至差分转换, 此款器件是这类应用的理想之选。片上匹配元件可对印刷电路板 (PCB) 实现方案进行简化, 并在可用带宽内提供最高性能。此器件采用德州仪器 (TI) 先进的互补 BiCMOS 工艺制造, 并采用航天级 LCCC 封装。

该器件由 3.3V 单轨电源供电。断电功能有助于实现节能。

器件信息

器件型号 ⁽¹⁾	等级	封装尺寸 ⁽²⁾
5962R2122001VXC	QMLV-RHA	FFM (LCCC, 12 引脚)
TRF0206FFM/EM	工程样片 ⁽³⁾	6.2mm × 6.1mm
TRF0206EVM	陶瓷评估板	—

- (1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。
- (2) 封装尺寸 (长 × 宽) 为标称值, 不包括引脚。
- (3) 这些器件仅适用于工程评估。这些样片按照非合规性流程进行加工处理。这些器件不适用于鉴定、量产、辐射测试或飞行用途。这些器件无法在完整 MIL 额定温度范围内或整个使用寿命中保证其性能。



驱动高速 ADC 的 TRF0206-SP



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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision A (December 2022) to Revision B (August 2023)	Page
• 向 器件信息 表添加了新的可订购器件型号.....	1
Changes from Revision * (November 2022) to Revision A (December 2022)	Page
• 将状态从 预告信息 更改为 量产数据	1

5 Pin Configuration and Functions

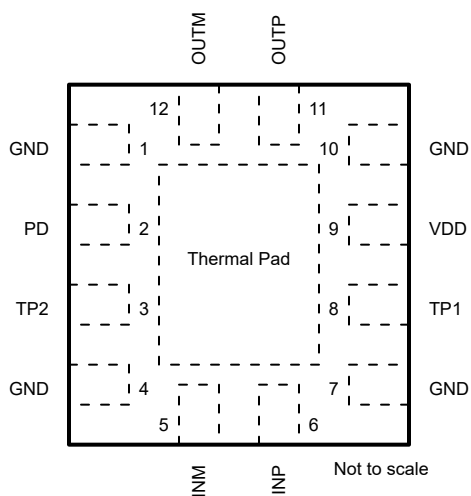


图 5-1. FFM Package, 12-Pin LCCC (Top View)

表 5-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NAME	NO.		
GND	1, 4, 7, 10	GND	Ground
INM	5	I	Differential signal input, negative
INP	6	I	Differential signal input, positive
OUTM	12	O	Differential signal output, negative
OUTP	11	O	Differential signal output, positive
PD	2	I	Power down signal. Supports 1.8-V and 3.3-V Logic. 0 = chip enabled 1 = power down
TP1	8	—	Test pin. Short to ground.
TP2	3	—	Test pin. Short to ground.
VDD	9	P	3.3-V supply
Thermal Pad	pad	—	Thermal pad. Connect to ground on board.

(1) I = input, O = output, P = power, GND = Ground

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{DD}	Supply voltage	– 0.3	3.7	V
INP, INM	Input pin power		20	dBm
V _{PD}	Power-down pin voltage	– 0.3	3.7	V
T _J	Junction temperature		150	°C
T _{stg}	Storage temperature	– 65	150	°C
	Continuous power dissipation	See thermal information		

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±1000	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002, all pins ⁽²⁾	±250	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{DD}	Supply voltage	3.2	3.3	3.45	V
T _A	Ambient air temperature	– 55	25		°C
T _J	Junction temperature			125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TRF0206-SP	UNIT
		FFM (LCCC)	
		12 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	69.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	54.5	°C/W
R _{θJB}	Junction-to-board thermal resistance	44.4	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	42	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	44.5	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	36.7	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

Specifications correspond to the respectively identified subgroup temperature, unless otherwise noted. Test conditions at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	SUBGROUP ⁽¹⁾	MIN	TYP	MAX	UNIT
AC PERFORMANCE							
SSBW	Small-signal 3-dB bandwidth	$V_o = 100\text{ mV}_{PP}$			6.5		GHz
LSBW	Large-signal 3-dB bandwidth	$V_o = 1\text{ V}_{PP}$			6.5		GHz
	Bandwidth for 1.5-dB flatness				4.8		GHz
S_{21}	Power gain	$f = 2\text{ GHz}$			12.5		dB
S_{11}	Input return loss	$f = 10\text{ MHz to }4\text{ GHz}$			-10		dB
S_{12}	Reverse isolation	$f = 10\text{ MHz to }4\text{ GHz}$			-35		dB
	Gain imbalance	$f = 10\text{ MHz to }5\text{ GHz}$			± 0.4		dB
	Phase imbalance	$f = 10\text{ MHz to }5\text{ GHz}$			± 3		°
CMRR	Common-mode rejection ratio ⁽²⁾	$f = 2\text{ GHz}$			-30		dB
HD2	Second-order harmonic distortion	$f = 0.5\text{ GHz}, P_o = +2\text{ dBm}$			-65		dBc
		$f = 1\text{ GHz}, P_o = +2\text{ dBm}$			-60		
		$f = 2\text{ GHz}, P_o = +2\text{ dBm}$			-60		
		$f = 4\text{ GHz}, P_o = +2\text{ dBm}$			-60		
HD3	Third-order harmonic distortion	$f = 0.5\text{ GHz}, P_o = +2\text{ dBm}$			-65		dBc
		$f = 1\text{ GHz}, P_o = +2\text{ dBm}$			-65		
		$f = 2\text{ GHz}, P_o = +2\text{ dBm}$			-68		
		$f = 4\text{ GHz}, P_o = +2\text{ dBm}$			-58		
OP1dB	Output 1-dB compression point	$f = 0.5\text{ GHz}$			8.5		dBm
		$f = 1\text{ GHz}$			10		
		$f = 2\text{ GHz}$			12		
		$f = 4\text{ GHz}$			10.5		
		$f = 6\text{ GHz}$			10		
OIP2	Output second-order intercept point	$f = 0.5\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			65		dBm
		$f = 1\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			62		
		$f = 2\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			58		
		$f = 4\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			55		
		$f = 6\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			55		
OIP3	Output third-order intercept point	$f = 0.5\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			32		dBm
		$f = 1\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			35		
		$f = 2\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			38		
		$f = 4\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			35		
		$f = 6\text{ GHz}, P_o = -5\text{ dBm per tone, }10\text{ MHz spacing}$			32		

6.5 Electrical Characteristics (continued)

Specifications correspond to the respectively identified subgroup temperature, unless otherwise noted. Test conditions at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$, unless otherwise noted.

PARAMETER		TEST CONDITIONS	SUBGROUP ⁽¹⁾	MIN	TYP	MAX	UNIT
NF	Noise figure	f = 0.5 GHz		7.5		dB	
		f = 1 GHz		7.5			
		f = 2 GHz		8			
		f = 4 GHz		9			
		f = 6 GHz		9			
IMPEDANCE							
Z _{O-DIFF}	Differential output impedance	f = dc (internal to the device)		5		Ω	
Z _{IN}	Single-ended input impedance	With INM terminated with 50 Ω		50		Ω	
TRANSIENT							
V _{OMAX}	Output max operating voltage (differential)			1.7		V _{PP}	
V _{OSAT}	Output saturated voltage level (differential)	f = 4 GHz		3.5		V _{PP}	
T _{REC}	Over-drive recovery time	Using a 0.5-V _P input pulse of 2-ns duration		0.35		ns	
POWER SUPPLY							
I _{QA}	Active current	Current on VDD pin, PD = 0	[1, 2, 3]	85	130	170	mA
I _{QPD}	Power-down quiescent current	Current on VDD pin, PD = 1	[1, 2, 3]	2	7	16	mA
ENABLE							
V _{PDHIGH}	PD pin logic high			1.55		V	
V _{PDLLOW}	PD pin logic low			0.7		V	
I _{PDBIAS}	PD bias current (current on PD pin)	PD = high (1.8-V logic)		50	100	μA	
		PD = low (3.3-V logic)		200	300		
C _{PD}	PD pin capacitance			3		pF	
T _{ON}	Turn-on time	50% V _{PD} to 90% RF		200		ns	
T _{OFF}	Turn-off time	50% V _{PD} to 10% RF		100		ns	

(1) For subgroup definitions, please see [Quality Conformance Inspection](#).

(2) CMRR is calculated using the formula $(S_{21}-S_{31}) / (S_{21}+S_{31})$. Port-1: INP, Port-2: OUTP, Port-3: OUTM.

6.6 Quality Conformance Inspection

SUBGROUP ⁽¹⁾	DESCRIPTION	TEMPERATURE (°C)
1	Static tests at	25
2	Static tests at	125
3	Static tests at	-55
4	Dynamic tests at	25
5	Dynamic tests at	125
6	Dynamic tests at	-55
7	Functional tests at	25
8A	Functional tests at	125
8B	Functional tests at	-55
9	Switching tests at	25
10	Switching tests at	125
11	Switching tests at	-55

(1) MIL-STD-883, Method 5005 - Group A

6.7 Typical Characteristics

at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$ (unless otherwise noted)

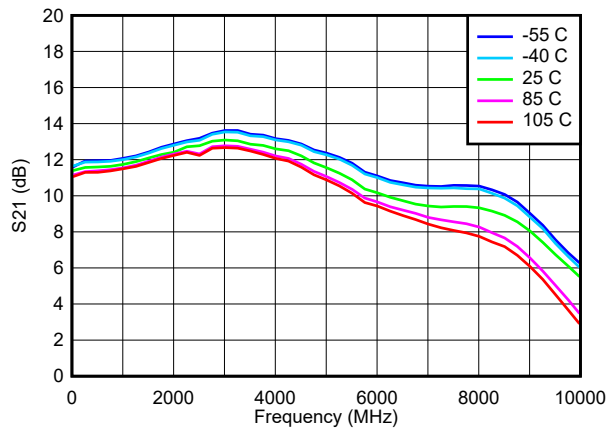


图 6-1. Power Gain Across Temperature

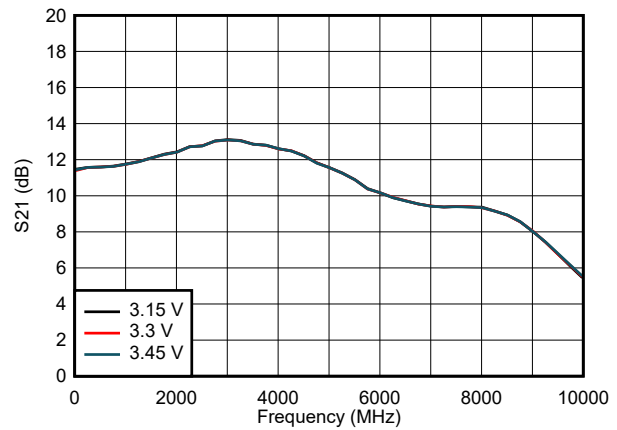


图 6-2. Power Gain Across VDD

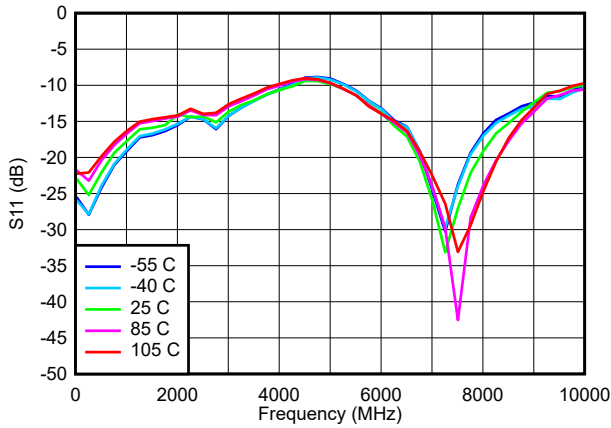


图 6-3. Return Loss Across Temperature

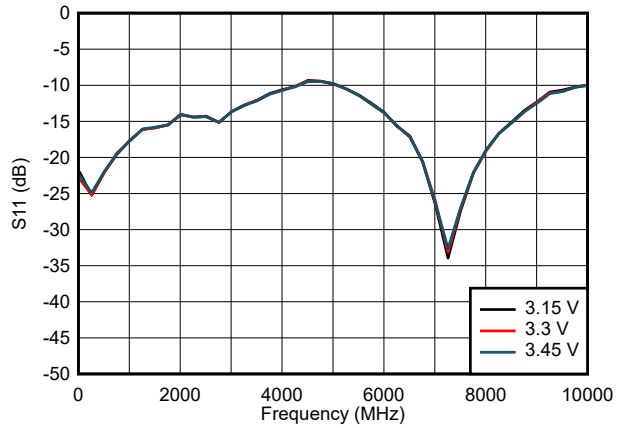


图 6-4. Return Loss Across VDD

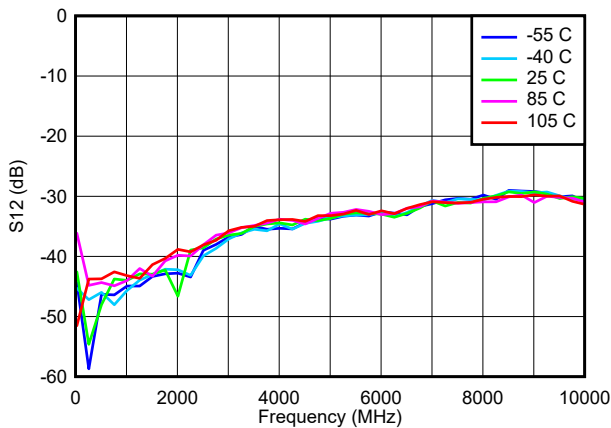


图 6-5. Reverse Isolation Across Temperature

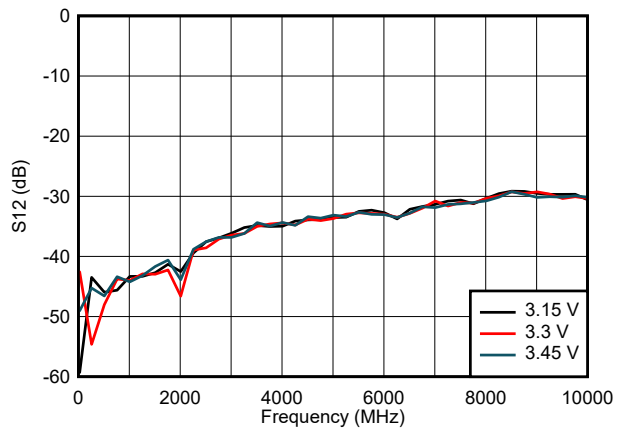
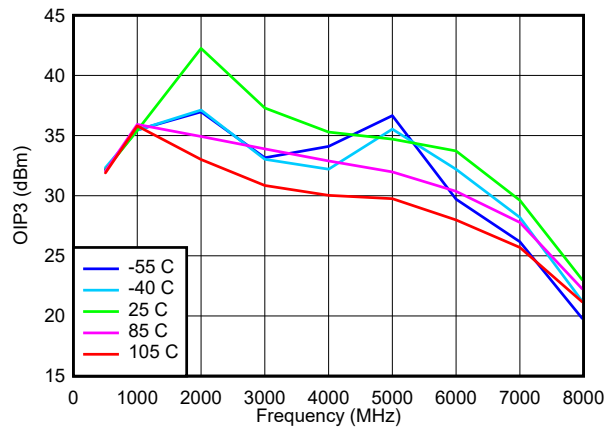


图 6-6. Reverse Isolation Across VDD

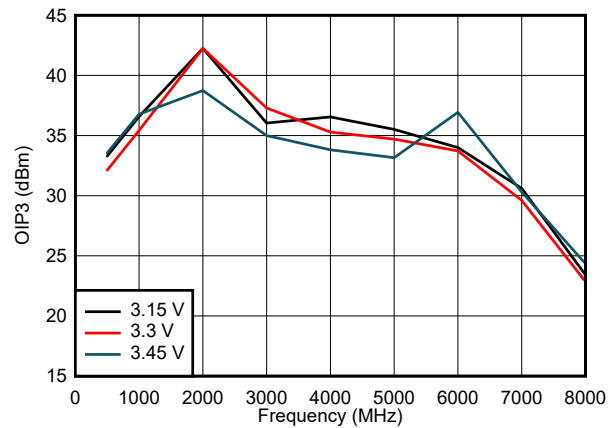
6.7 Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$ (unless otherwise noted)



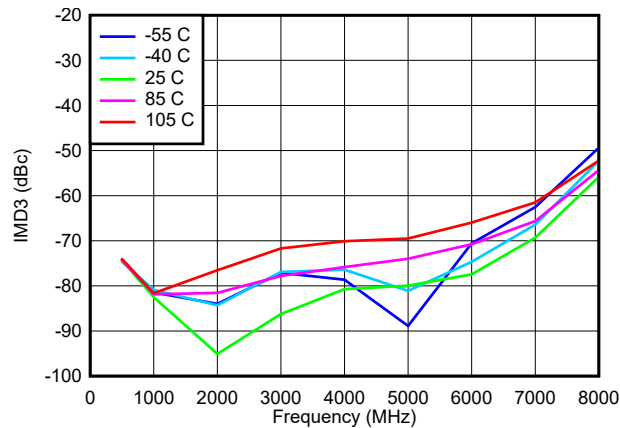
Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-7. OIP3 Across Temperature



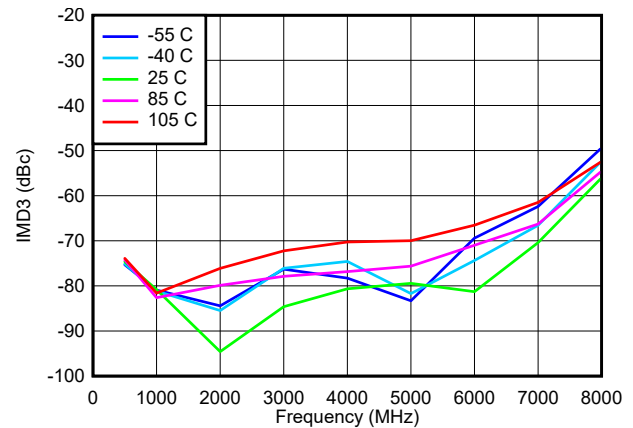
Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-8. OIP3 Across VDD



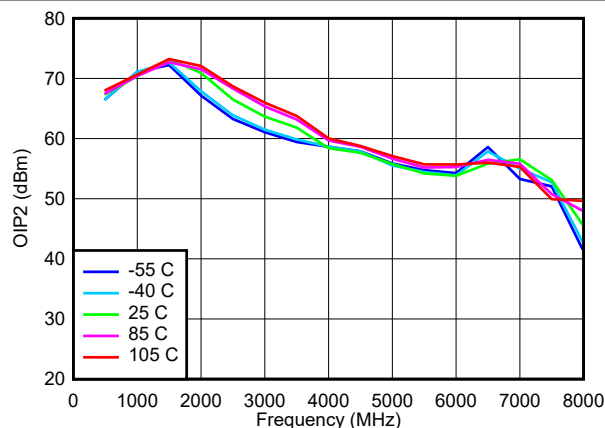
At $(2f_1 - f_2)$ frequency; $f_2 > f_1$, Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-9. IMD3 Lower Frequency



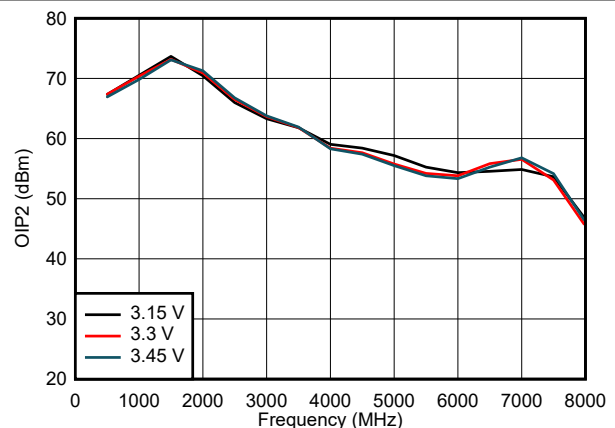
At $(2f_2 - f_1)$ frequency; $f_2 > f_1$, Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-10. IMD3 Higher Frequency



At $(f_2 - f_1)$ frequency; $f_2 > f_1$, Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-11. OIP2 Lower Frequency Across Temperature

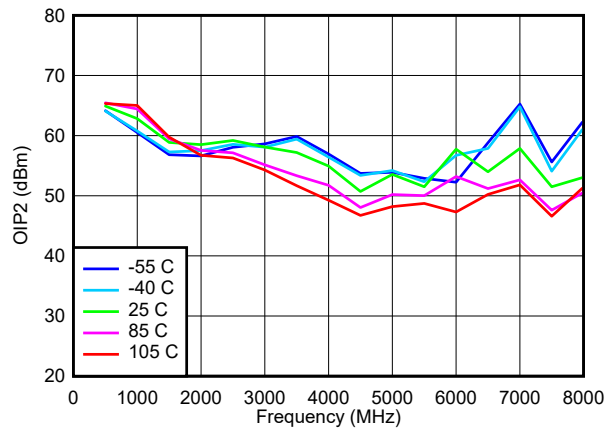


At $(f_2 - f_1)$ frequency; $f_2 > f_1$, Pout / tone = -5 dBm, 10-MHz tone spacing

图 6-12. OIP2 Lower Frequency Across VDD

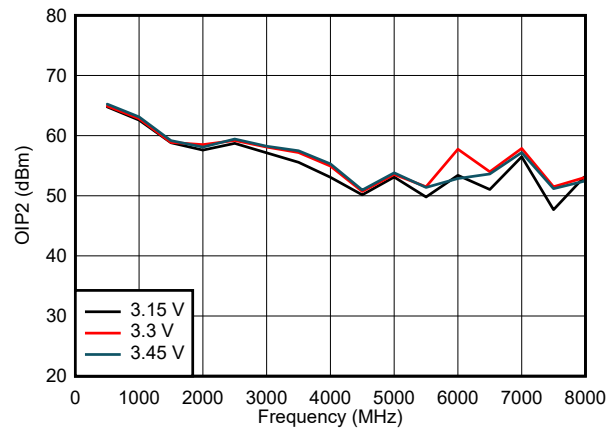
6.7 Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$ (unless otherwise noted)



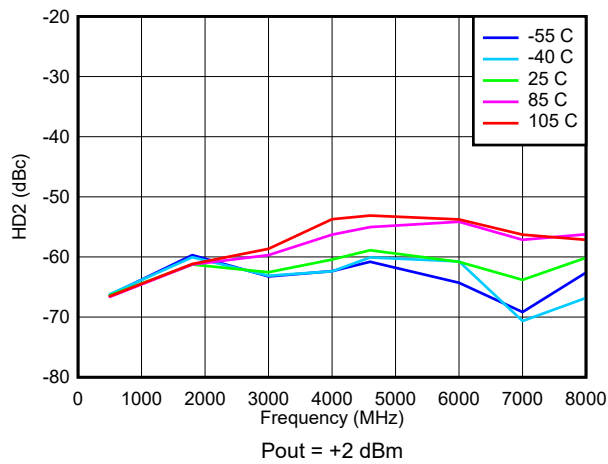
At (f_2+f_1) frequency; $f_2 > f_1$, P_{out} / tone = -5 dBm,
10-MHz tone spacing

图 6-13. OIP2 Higher Frequency Across Temperature



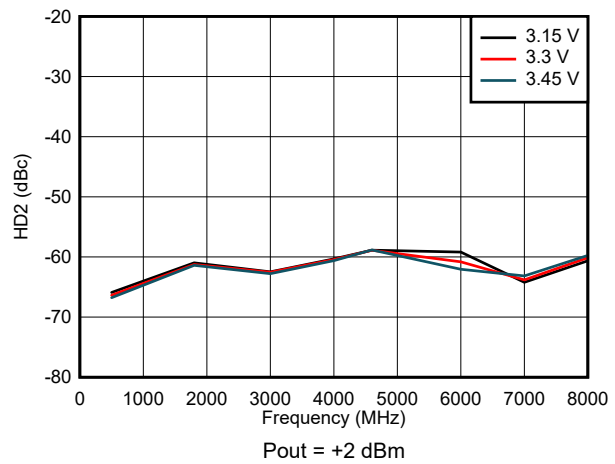
At (f_2+f_1) frequency; $f_2 > f_1$, P_{out} / tone = -5 dBm,
10-MHz tone spacing

图 6-14. OIP2 Higher Frequency Across VDD



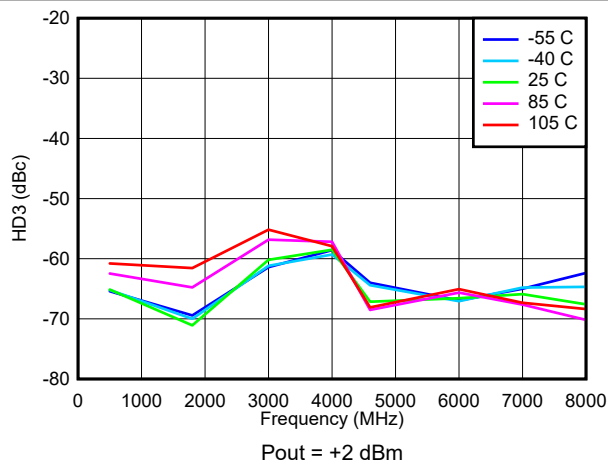
$P_{out} = +2\text{ dBm}$

图 6-15. HD2 Across Temperature



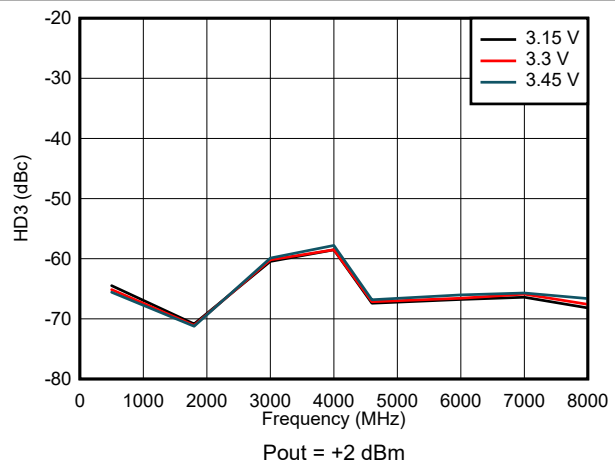
$P_{out} = +2\text{ dBm}$

图 6-16. HD2 Across VDD



$P_{out} = +2\text{ dBm}$

图 6-17. HD3 Across Temperature



$P_{out} = +2\text{ dBm}$

图 6-18. HD3 Across VDD

6.7 Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$ (unless otherwise noted)

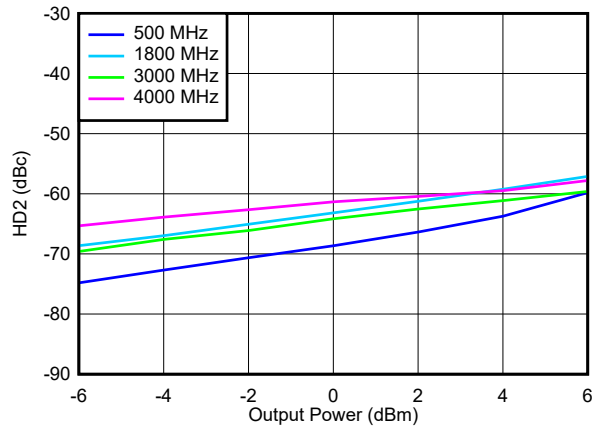


图 6-19. HD2 vs Output Power

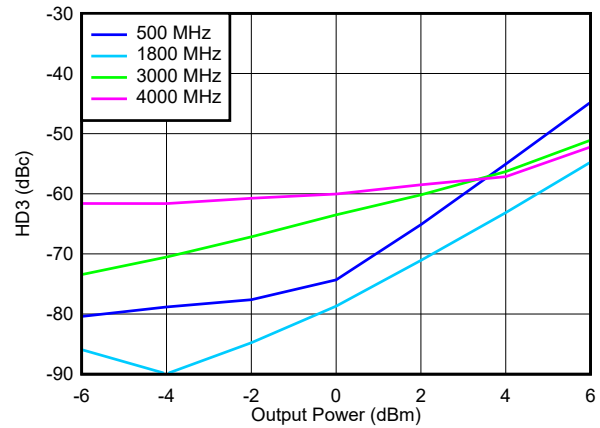


图 6-20. HD3 vs Output Power

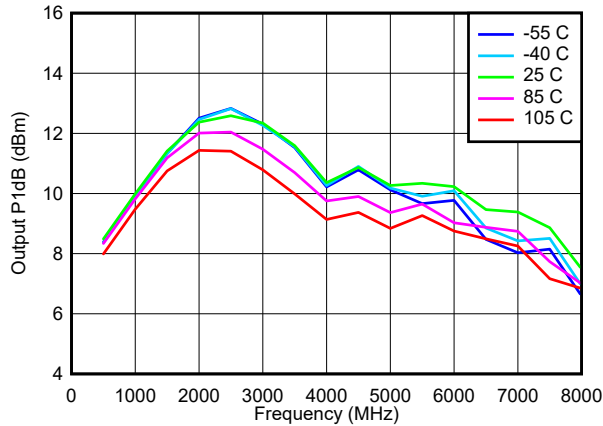


图 6-21. Output P1 dB Across Temperature

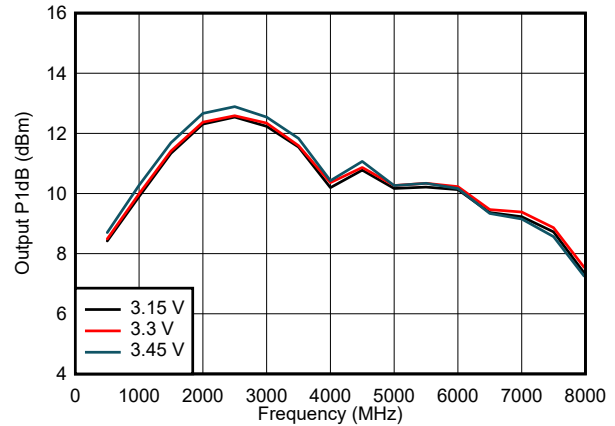


图 6-22. Output P1 dB Across VDD

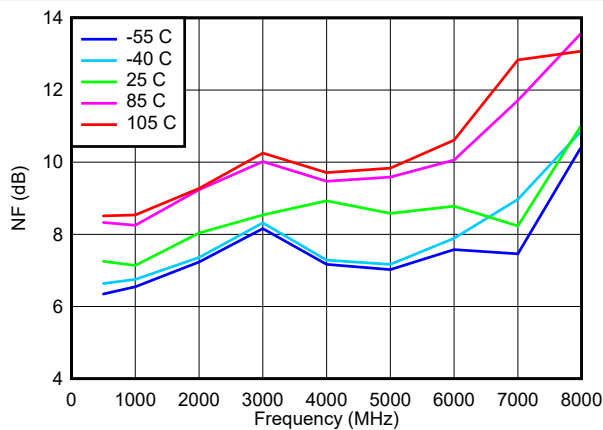


图 6-23. NF Across Temperature

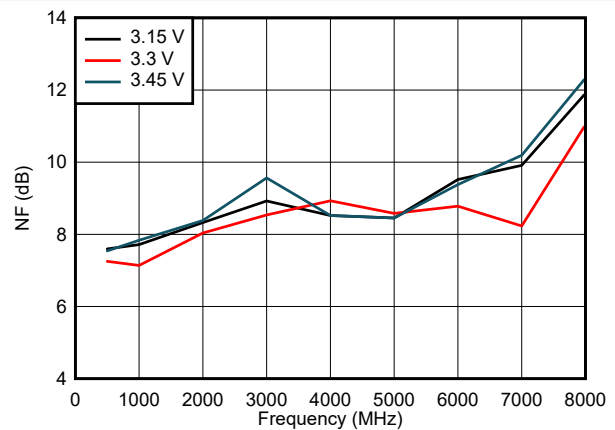


图 6-24. NF Across VDD

6.7 Typical Characteristics (continued)

at $T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{ V}$, single-ended input with $R_S = 50\ \Omega$, differential output with $Z_L = 100\ \Omega$ (unless otherwise noted)

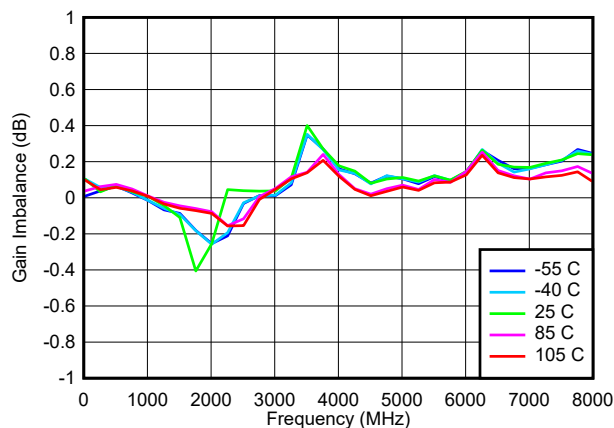


图 6-25. Gain Imbalance

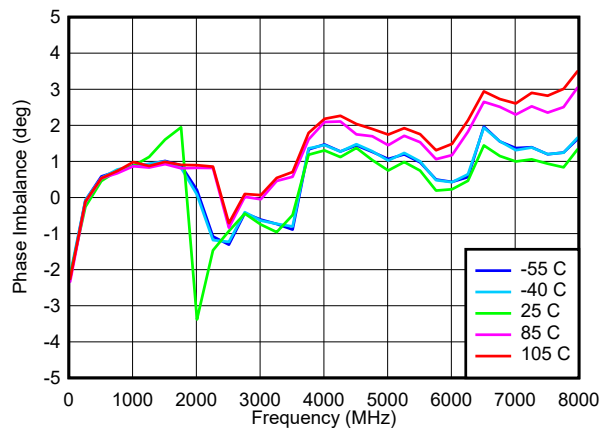


图 6-26. Phase Imbalance

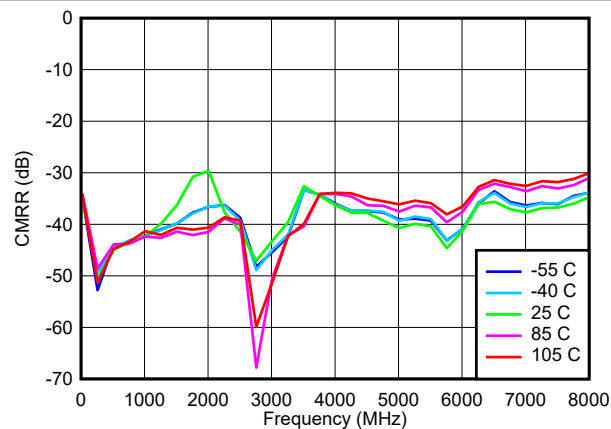


图 6-27. CMRR Across Temperature

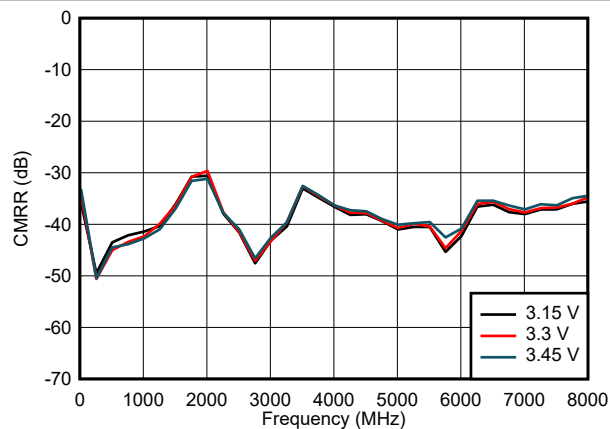


图 6-28. CMRR Across VDD

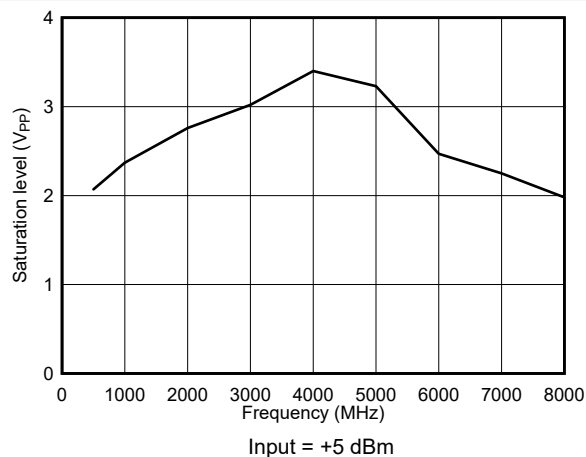


图 6-29. Saturation Voltage

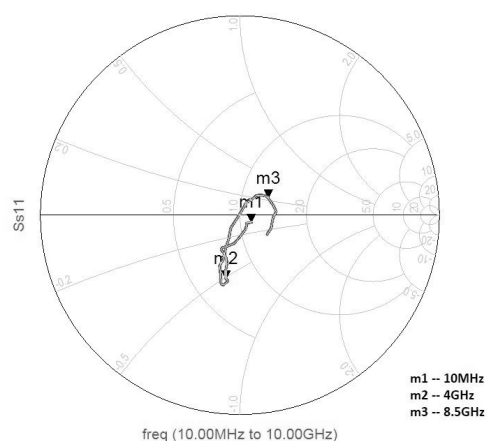


图 6-30. Single-Ended S11

7 Detailed Description

7.1 Overview

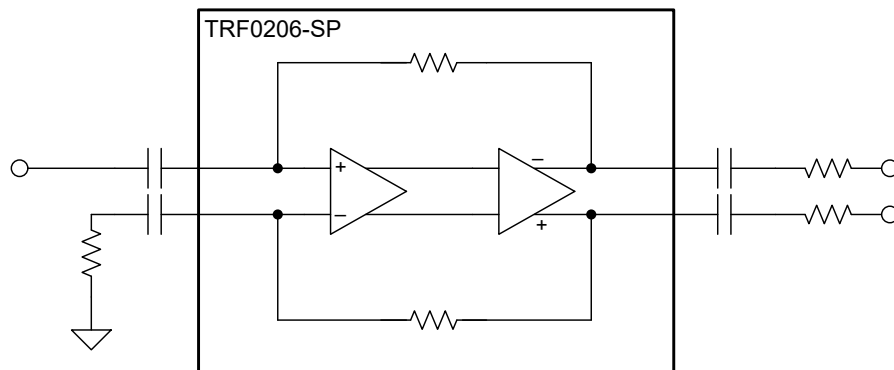
The TRF0206-SP is a very high-performance amplifier optimized for radio frequency (RF) and intermediate frequency (IF) with signal bandwidths up to 7 GHz. This device is an excellent choice for ac-coupled applications that require a single-ended to differential conversion when driving an analog-to-digital converter (ADC). The device has a two-stage architecture and provides approximately 13 dB of gain when configured for single-ended inputs driven from a 50- Ω source. This device also works as a differential-to-single-ended amplifier to act as a DAC buffer.

This TRF0206-SP does not require any pullup or pulldown components on the PCB, and thereby simplifies the layout and provides the highest performance over the whole bandwidth.

The input and output are ac coupled. The device is powered with 3.3-V supply. A power-down feature is also available.

7.2 Functional Block Diagram

The following figure shows the functional block diagram of the TRF0206-SP. The device essentially has two stages with a voltage-feedback configuration.



7.3 Feature Description

7.3.1 Fully Differential Amplifier

The TRF0206-SP is a voltage-feedback fully differential amplifier (FDA) with a fixed gain by architecture. The TRF0206-SP operates best as a single-ended to differential amplifier by terminating the INM pin with a 50- Ω resistor and driving the INP pin directly with no external components.

This amplifier has nonlinearity cancellation circuits that provide excellent linearity performance over a wide range of frequencies.

The output of the amplifier has a low dc impedance. Therefore, if required, the output of the amplifier can be matched to a load by adding appropriate series resistors or attenuator pad.

7.3.2 Single-Supply Operation

The TRF0206-SP operates on a single, 3.3-V supply. The input and output bias voltages are set internally. Therefore, ac-couple the signal path on the board at all four RF input and output pins. Single-supply operation simplifies the board design.

7.4 Device Functional Modes

The TRF0206-SP has two functional modes: active and power-down. These functional modes are controlled by the PD pin as described in the previous section.

7.4.1 Power-Down Mode

The device features a power-down option. The PD pin is used to power down the amplifier. This pin supports both 1.8-V and 3.3-V digital logic, and is referenced to ground. A logic 1 turns the device off and places the device into a low-quiescent-current state.

When disabled, the signal path is still present through the internal circuits. Input signals applied to a disabled device still appear at the outputs at some lower level through this path, as is the case for any disabled feedback amplifier.

8 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Application Information

8.1.1 Driving a High-Speed ADC

A common application of the TRF0206-SP is to drive a high-speed ADC, such as the [ADC12DJ3200QML-SP](#) or [AFE7950](#) that have differential inputs. Conventionally, passive baluns are used to drive GSPS ADCs because of nonavailability of high-bandwidth linear amplifiers. The TRF0206-SP is an active balun that has excellent bandwidth flatness, gain, and phase imbalance comparable to or exceeding costly passive baluns.

The following figure shows a typical interface circuit for the ADC12DJ3200QML-SP. Depending on the ADC and system requirement, this circuit can be simplified or can be more complex.

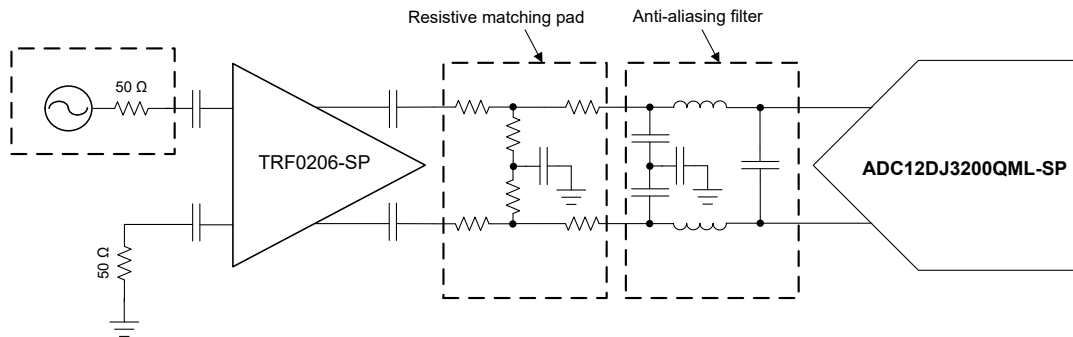


图 8-1. Interfacing with High-Speed ADC

图 8-1 shows two sections of the circuit between the driver amp and the ADC: namely, the matching pad (or attenuator pad) and the antialiasing filter. Use small form-factor, RF-quality, passive components for these circuits. The output swing of the TRF0206-SP is designed to drive these ADCs full-scale, while at the same time not overdrive the device. This functionality avoids the need for any voltage limiting device at the ADC.

8.1.2 Calculating Output Voltage Swing

This section gives a quick reference of the output voltage swings for different input power levels. In this example, the output is terminated with a 100-Ω differential load and a power gain of 13 dB is assumed.

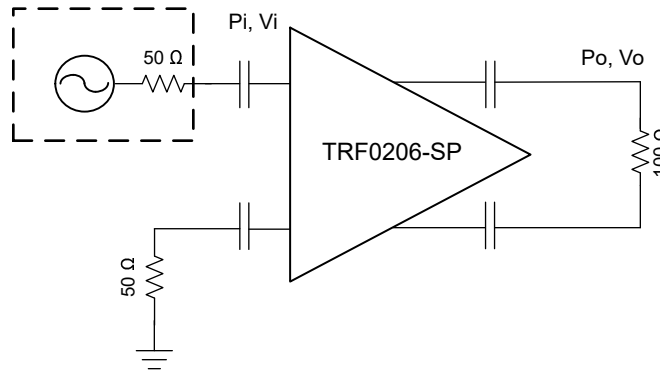


图 8-2. Power and Voltage Levels

$$\text{Voltage gain} = 20 \times \log(V_o / V_i) \quad (1)$$

$$\text{Power gain} = 10 \times \log(P_o / P_i) = 10 \times \log((V_o^2 / 100) / (V_i^2 / 50)) = 20 \times \log(V_o / V_i) - 3 \text{ dB} \quad (2)$$

表 8-1. Output Voltage Swings for Different Input Power Levels

INPUT		OUTPUT	
P _i (dBm)	V _i (V _{PP})	P _o (dBm)	V _o (V _{PP})
-20	0.063	-7	0.4
-15	0.112	-2	0.71
-10	0.2	3	1.263
-7	0.283	6	1.785

8.1.3 Thermal Considerations

The TRF0206-SP is packaged in a 6.10 mm × 6.20 mm LCCC-FC package that has excellent thermal properties. Connect the device thermal pad to a ground plane. Short the ground plane to the other ground pins of the device at four corners, if possible, to allow heat propagation to the top layer of the PCB. Use a thermal via that connects the thermal pad plane on the top layer of the PCB to the inner layer ground planes to allow heat propagation to the inner layers.

Limit the total power dissipation to keep the device junction temperature less than 150°C for instantaneous power and less than 125°C for continuous power.

8.2 Typical Application

8.2.1 TRF0206-SP Driving an AFE7950-SP Receiver

This section describes an RF receiver chain in which the TRF0206-SP is working as a single-ended to differential (S2D) amplifier and driving a receive channel of the AFE7950-SP.

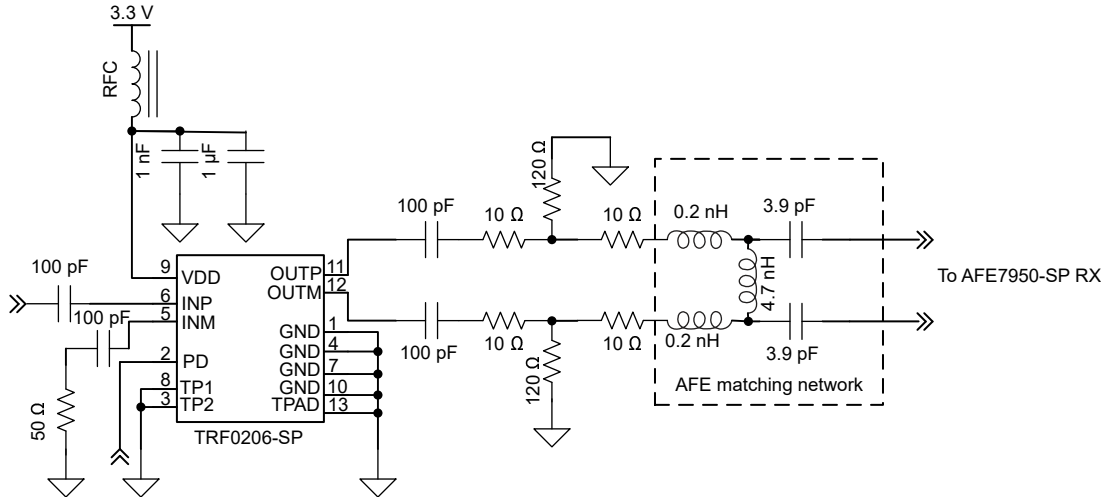


图 8-3. The TRF0206-SP in a Receive Chain Driving the AFE7950-SP ADC

图 8-3 is a generic schematics of a design in which the TRF0206-SP drives an AFE7950-SP receive channel. The exact values of the components depend on the frequency band for which the AFE7950-SP front-end is matched.

8.2.1.1 Design Requirements

The AFE7950-SP receive channel is required to be matched to 2.3 GHz.

8.2.1.2 Detailed Design Procedure

The TRF0206-SP is configured as an S2D amplifier. The section close to the TRF0206-SP output is an attenuator pad that is meant for robust matching. The section close to AFE7950-SP is the matching network for the AFE that is channel and channel-frequency dependent. The matching components are chosen based on the AFE return-loss data and some trial and error because the manufactured board parameters can influence the exact component values.

8.3 Power Supply Recommendations

The TRF0206-SP requires a single 3.3-V supply. Supply decoupling is critical to high-frequency performance. Typically two or three capacitors are used for supply decoupling. Place the lowest-value capacitor, a small form-factor component, closest to the VDD pin of the device. Place a bulk decoupling capacitor that has a larger value and size next to the small capacitor. Additional layout recommendations are given in the *Layout* section.

8.4 Layout

8.4.1 Layout Guidelines

TRF0206-SP is a wide-band feedback amplifier with approximately 13 dB of gain. When designing with a wideband RF amplifier with relatively high gain, take certain board layout precautions to maintain stability and optimal performance. Use a multilayered board to maintain signal and power integrity and thermal performance. The following figure shows an example of a good layout. In this figure, only the top layer is shown.

Route the RF input and output lines as grounded coplanar waveguide (GCPW) lines. Make sure the second layer is a continuous ground layer without any ground-cuts near the amplifier area. Match the output differential lines in length to minimize phase imbalance. Use small footprint passive components wherever possible. Also take care of the input side layout. Route the INP with a 50- Ω line. Make sure that the NM pin termination has low parasitics by placing the ac-coupling capacitor and the 50- Ω resistor very close to the device. Use an RF quality 50- Ω resistor for termination. Make sure that ground planes on the top and internal layers are well stitched with vias.

As [Figure 8-4](#) shows, place thermal vias under the device that connect the top thermal pad with ground planes in the inner layers of the PCB. Also connect the thermal pad to the top layer ground plane through the ground pins.

8.4.2 Layout Example

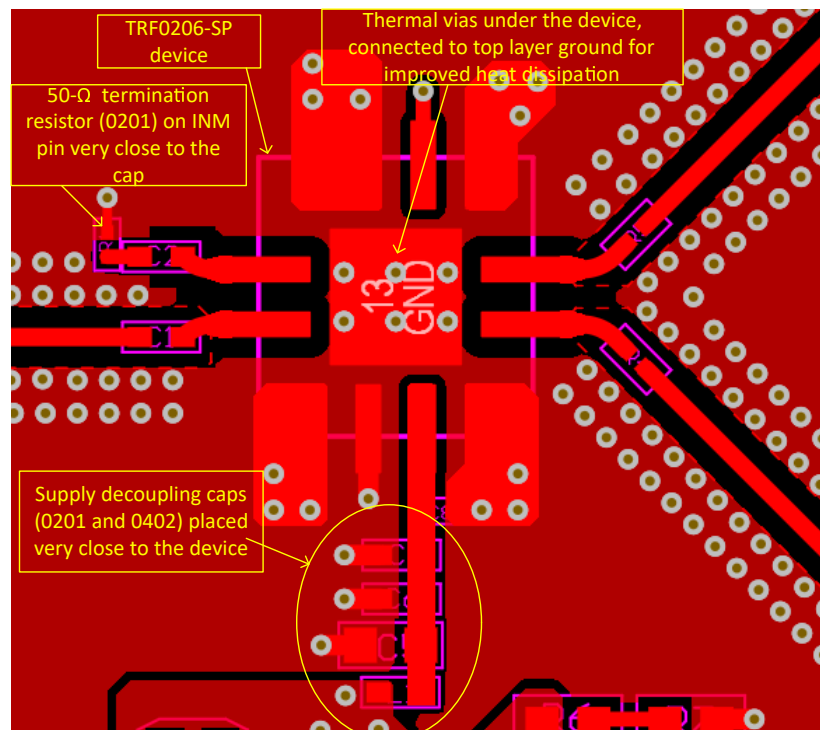


图 8-4. Layout Example: Placement and Top Layer Layout

The TRF0206-SP can be evaluated using the TRF0206-SP EVM board, which can be ordered from the [TRF0206-SP product folder](#). Additional information about the evaluation board construction and test setup is given in the [TRF0206-SP EVM User's Guide](#).

9 Device and Documentation Support

9.1 Device Support

9.1.1 第三方产品免责声明

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9.2 Documentation Support

9.2.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [TRF0206-SP EVM User's Guide](#)

9.3 接收文档更新通知

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9.4 支持资源

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.7 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962R2122001VXC	Active	Production	LCCC (FFM) 12	50 JEDEC TRAY (5+1)	No	Call TI	N/A for Pkg Type	-55 to 125	5962R 2122001VXC TRF0206FFM
TRF0206FFM/EM	Active	Production	LCCC (FFM) 12	50 JEDEC TRAY (5+1)	No	Call TI	N/A for Pkg Type	25 to 25	TRF0206FFM/EM

- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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LCCC - 1.78 mm max height

LEADLESS CERAMIC CHIP CARRIER



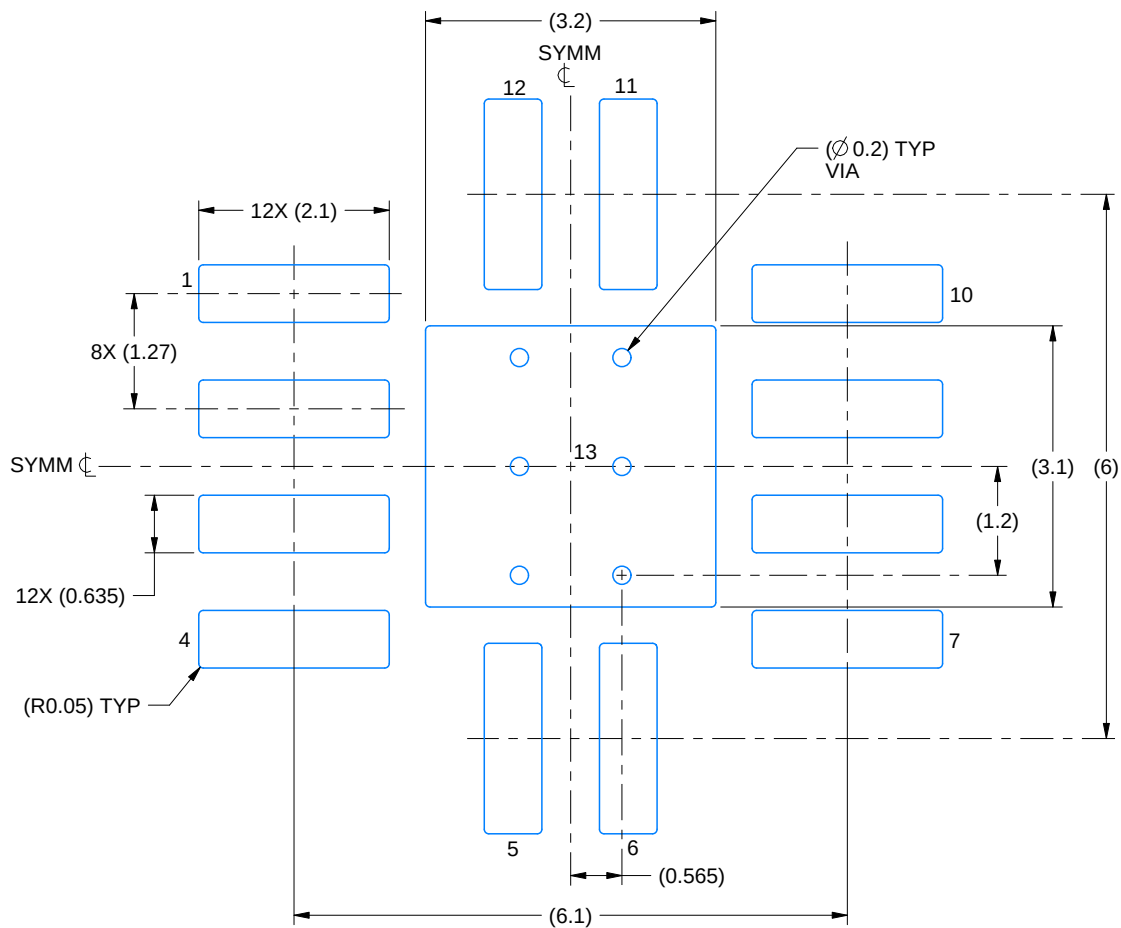
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The terminals are gold-plated.

EXAMPLE BOARD LAYOUT

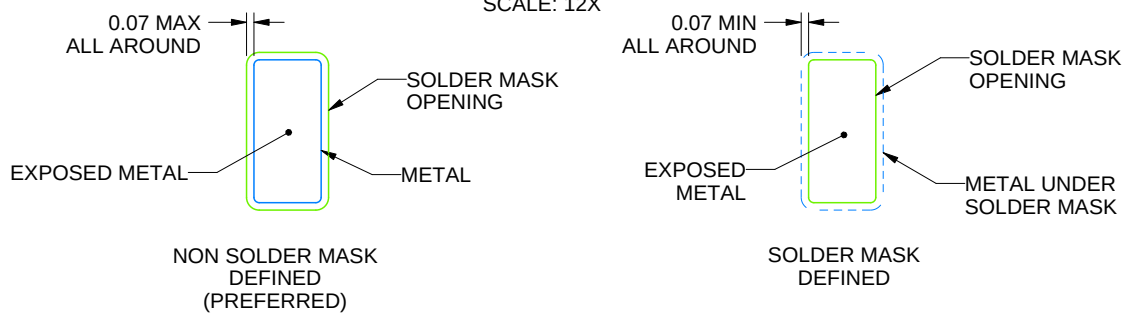
FFM0012A

LCCC - 1.78 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 12X



SOLDER MASK DETAILS
NOT TO SCALE

4226328/D 01/2021

NOTES: (continued)

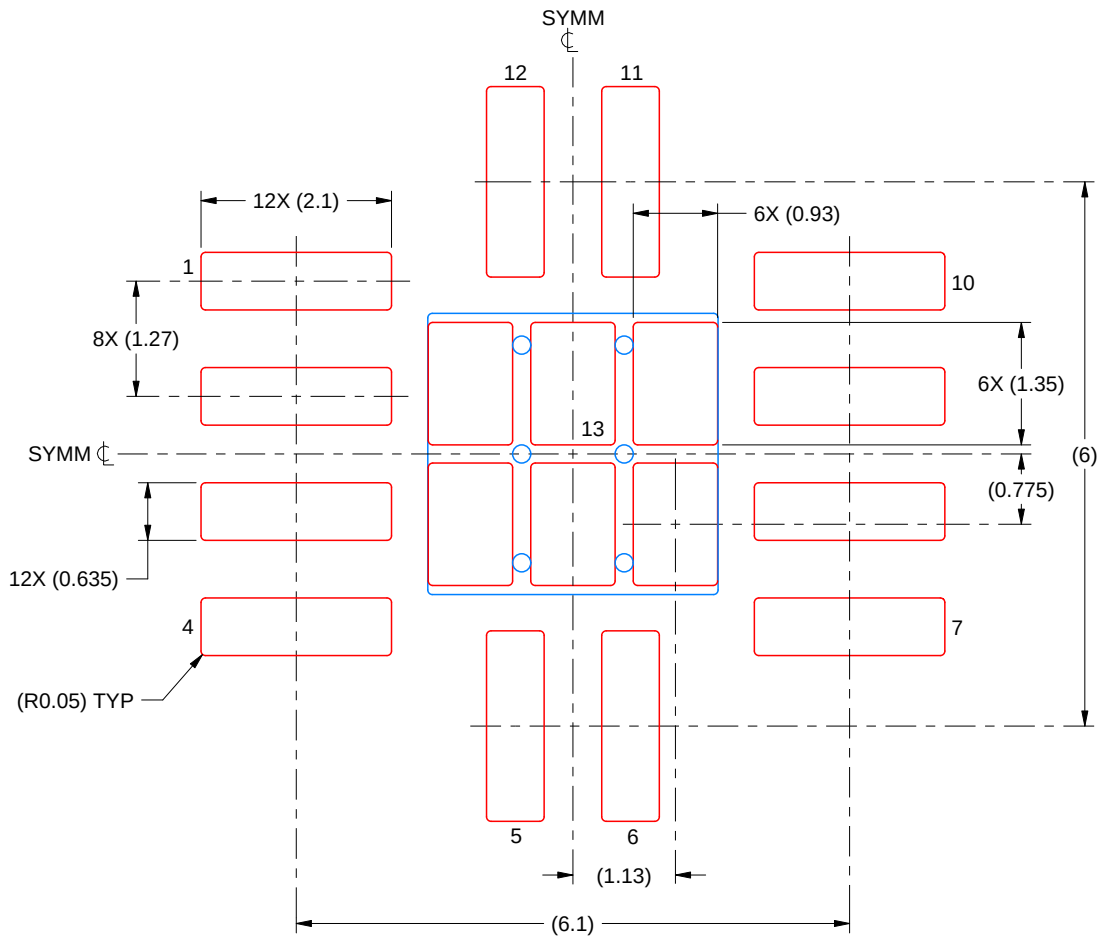
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

FFM0012A

LCCC - 1.78 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 13:
76% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE: 12X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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